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## Product Change Notification - JAON-15JIKR494

**Date:** 28 Jun 2016  
**Product Category:** Analog (Thermal, Power Management & Safety); Analog (Linear & Mixed Signal) AND Interface  
**Notification subject:** CCB 2542 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for products fabricated at XFGM available in 8L PDIP package at MMT assembly site.  
**Notification text:** **PCN Status:**  
Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for products fabricated at XFGM available in 8L PDIP package at MMT assembly site.

**Pre Change:**

Gold (Au) bond wire

**Post Change:**

Palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	MMT assembly site	MMT assembly site
<b>Wire material</b>	Au wire	CuPdAu wire
<b>Die attach material</b>	CRM-1064L	CRM-1064L
<b>Molding compound material</b>	GE800	GE800
<b>Lead frame material</b>	CDA194	CDA194

**Impacts to Data Sheet:**  
None

**Reason for Change:**  
To improve productivity and qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**  
In Progress

**Estimated First Ship Date:**  
July 11, 2016 (date code: 1628)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	March 2016					-->	June 2016					July 2016			
Workweek	09	10	11	12	13		22	23	24	25	26	27	28	29	30
Initial PCN Issue Date	X														
Qual Report Availability											X				
Final PCN Issue Date											X				
Implementation Date													X		

**Markings to Distinguish Revised from Unrevised Devices:**  
Traceability code

**Revision History:**  
**March 2, 2016:** Issued initial notification.  
**June 28, 2016:** Issued final notification. Attached the qualification report. Revised the estimated first ship date from June 30, 2016 to July 11, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-15JIKR494\\_Qual\\_Report.pdf](#)  
[PCN\\_JAON-15JIKR494\\_Affected\\_CPN.pdf](#)  
[PCN\\_JAON-15JIKR494\\_Affected\\_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15JIKR494
CATALOG_PART_NBR
MCP2003A-E/P
MCP2003-E/P
MCP2004A-E/P
MCP2004-E/P
MCP2021A-330E/P
MCP2021A-500E/P
MCP2025-330E/P
MCP2025-500E/P
MCP2551-E/P
MCP2551-I/P
RE46C100E8F
RE46C101E8F
RE46C108E8F
RE46C112E8F
RE46C114E8F
RE46C117E8F
RE46C317E8F
RE46C318E8F